ABSTRACT

MULTI-LEVEL INTEGRATED CIRCUIT FOR WIDE-GAP SUBSTRATE BONDING

An integrated circuit (30) includes a substrate (10) having an etched surface and a non-etched surface. The etched surface contains circuit elements (22, 24) and the non-etched surface contains a bonding surface (18). The non-etched surface is located at a predetermined height (12) from the etched surface. Bonding this integrated circuit (30) with another substrate creates a wide-gap between the substrates that is preferably evacuated and hermetically scaled.



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